

Docket No.: MAS-FIN-116

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J1017 U.S. PTO
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : JOHANN WINDERL ET AL.

Filed : CONCURRENTLY HEREWITH

Title : ELECTRONIC COMPONENT WITH A SEMICONDUCTOR CHIP
AND METHOD OF PRODUCING AN ELECTRONIC
COMPONENT

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications
are submitted herewith:

U.S. Patent 5,879,964 (Paik et al.), dated March 9, 1999;

U.S. Patent 6,043,109 (Yang et al.), dated March 28, 2000;

German Patent Application DE 37 20 465 C2 (Son), dated December 29, 1988,
primer dissolution to produce a dissolvable layer for negative photoresists on a silicon
wafer;

German Patent Application DE 43 33 407 C1 (Probst et al.), dated November 17,
1994, solar cell having a chalcopyrite absorber layer;

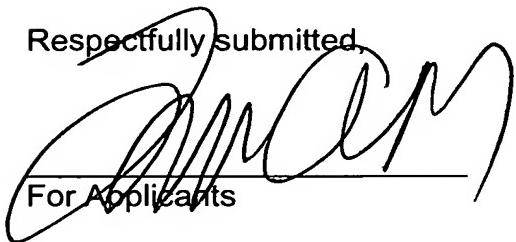
German Published Non-Prosecuted Patent Application DE 195 00 655 A1 (Zakel et
al.), dated July 18, 1996, chip support arrangement and chip support for the
manufacture of a chip casing;

German Published Non-Prosecuted Patent Application DE 196 36 112 A1 (Houdeau et al.), dated March 12, 1998, carrier element for a semiconductor chip;

European Patent Application EP 0 980 096 A1 (Fukutomi et al.), dated February 16, 2000.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,



For Applicants

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Date: February 20, 2002

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